


## APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

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| <b>Title of Invention</b>   | [WAFER STRUCTURE AND BUMPING PROCESS THEREOF] |  |  |
| Application Type : regular, utility<br>Attorney Docket Number : 11579-US-PA   |   |  |  |
| Correspondence address:<br>Customer Number: 31561<br>  |   |  |  |
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as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.